



FDMD8530

Dual N-Channel PowerTrench[®] MOSFET

Q1: 30 V, 201 A, 1.25 mΩ Q2: 30 V, 201 A, 1.25 mΩ

Features

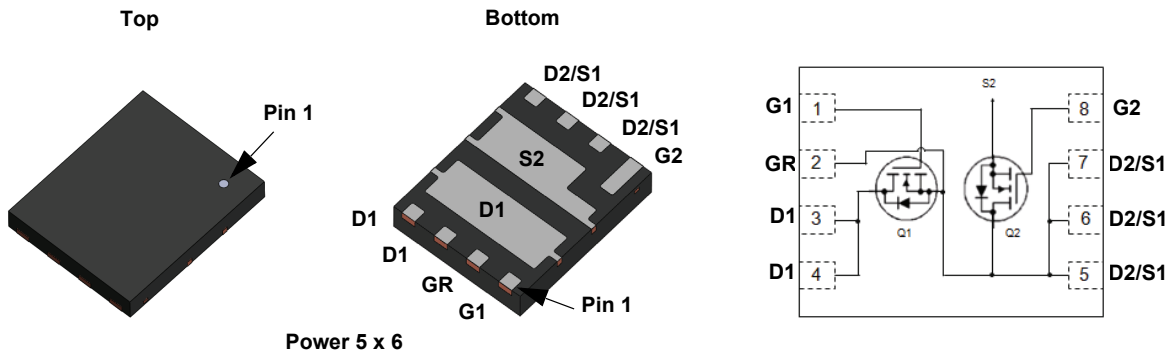
- Q1: N-Channel
 - Max $r_{DS(on)}$ = 1.25 mΩ at $V_{GS} = 10\text{ V}$, $I_D = 35\text{ A}$
 - Max $r_{DS(on)}$ = 1.5 mΩ at $V_{GS} = 4.5\text{ V}$, $I_D = 32\text{ A}$
- Q2: N-Channel
 - Max $r_{DS(on)}$ = 1.25 mΩ at $V_{GS} = 10\text{ V}$, $I_D = 35\text{ A}$
 - Max $r_{DS(on)}$ = 1.5 mΩ at $V_{GS} = 4.5\text{ V}$, $I_D = 32\text{ A}$
- Ideal for Flexible Layout in Primary Side of Bridge Topology
- 100% UIL Tested
- Kelvin High Side MOSFET Drive Pin-out Capability
- RoHS Compliant

General Description

This device includes two 30V N-Channel MOSFETs in a dual power (5 mm X 6 mm) package. HS source and LS drain internally connected for half/full bridge, low source inductance package, low $r_{DS(on)}$ /Qg FOM silicon.

Applications

- POL Synchronous Dual
- One Phase Motor Half Bridge
- Half/Full Bridge Secondary Synchronous Rectification



MOSFET Maximum Ratings $T_A = 25\text{ °C}$ unless otherwise noted.

Symbol	Parameter	Q1	Q2	Units
V_{DS}	Drain to Source Voltage	30	30	V
V_{GS}	Gate to Source Voltage	±20	±20	V
I_D	Drain Current -Continuous	$T_C = 25\text{ °C}$ (Note 5)	201	201
	-Continuous	$T_C = 100\text{ °C}$ (Note 5)	127	127
	Drain Current -Continuous	$T_A = 25\text{ °C}$	35 ^{1a}	35 ^{1b}
	-Pulsed	(Note 4)	1047	1047
E_{AS}	Single Pulse Avalanche Energy	(Note 3)	661	661
P_D	Power Dissipation	$T_C = 25\text{ °C}$	78	78
	Power Dissipation	$T_A = 25\text{ °C}$	2.2 ^{1a}	2.2 ^{1b}
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150		°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.6	1.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	55 ^{1a}	55 ^{1b}	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMD8530	FDMD8530	Power 5 x 6	13"	12 mm	3000 units

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Type	Min.	Typ.	Max.	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$	Q1 Q2	30 30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$	Q1 Q2		20 20		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}$, $V_{GS} = 0\text{ V}$	Q1 Q2			1 1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$	Q1 Q2			± 100 ± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\text{ }\mu\text{A}$	Q1 Q2	1.0 1.0	1.5 1.5	3.0 3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$	Q1 Q2		-5 -5		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$, $I_D = 35\text{ A}$	Q1		0.77	1.25	m Ω
		$V_{GS} = 4.5\text{ V}$, $I_D = 32\text{ A}$			0.96	1.5	
		$V_{GS} = 10\text{ V}$, $I_D = 35\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$			1.1	1.8	
		$V_{GS} = 10\text{ V}$, $I_D = 35\text{ A}$	Q2		0.77	1.25	
		$V_{GS} = 4.5\text{ V}$, $I_D = 32\text{ A}$			0.96	1.5	
		$V_{GS} = 10\text{ V}$, $I_D = 35\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$			1.1	1.8	
g_{FS}	Forward Transconductance	$V_{DD} = 5\text{ V}$, $I_D = 35\text{ A}$	Q1 Q2		259 259		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}$, $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	Q1 Q2		7425 7425	10395 10395	pF
C_{oss}	Output Capacitance		Q1 Q2		2190 2190	3070 3070	pF
C_{rss}	Reverse Transfer Capacitance		Q1 Q2		220 220	310 310	pF
R_g	Gate Resistance		Q1 Q2	0.1 0.1	1.9 1.9	3.8 3.8	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}$, $I_D = 35\text{ A}$ $V_{GS} = 10\text{ V}$, $R_{GEN} = 6\text{ }\Omega$	Q1 Q2		14 14	25 25	ns
t_r	Rise Time		Q1 Q2		13 13	24 24	ns
$t_{d(off)}$	Turn-Off Delay Time		Q1 Q2		71 71	114 114	ns
t_f	Fall Time		Q1 Q2		21 21	34 34	ns
$Q_{g(TOT)}$	Total Gate Charge		$V_{GS} = 0\text{ V to }10\text{ V}$	Q1 Q2		106 106	149 149
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0\text{ V to }4.5\text{ V}$	Q1 Q2		50 50	70 70	nC
Q_{gs}	Gate to Source Charge	$V_{DD} = 15\text{ V}$, $I_D = 35\text{ A}$	Q1 Q2		16 16		nC
Q_{gd}	Gate to Drain "Miller" Charge		Q1 Q2		13 13		nC

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted.

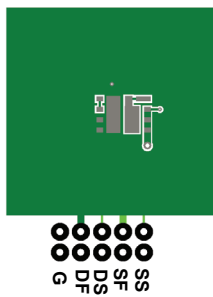
Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
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Drain-Source Diode Characteristics

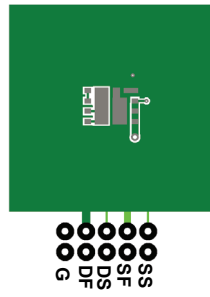
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 35\text{ A}$ (Note 2)	Q1 Q2		0.8 0.8	1.3 1.3	V
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 2\text{ A}$ (Note 2)	Q1 Q2		0.7 0.7	1.2 1.2	V
t_{rr}	Reverse Recovery Time	$I_F = 35\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	Q1 Q2		54 54	87 87	ns
Q_{rr}	Reverse Recovery Charge		Q1 Q2		39 39	63 63	nC

NOTES:

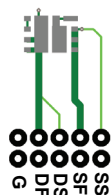
1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta CA}$ is determined by the user's board design.



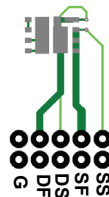
a. 55 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 55 °C/W when mounted on a 1 in² pad of 2 oz copper



c. 155 °C/W when mounted on a minimum pad of 2 oz copper



d. 155 °C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0 %.

3. Q1: E_{AS} of 661 mJ is based on starting $T_J = 25\text{ }^\circ\text{C}$, $L = 3\text{ mH}$, $I_{AS} = 21\text{ A}$, $V_{DD} = 30\text{ V}$, $V_{GS} = 10\text{ V}$. 100% tested at $L = 0.1\text{ mH}$, $I_{AS} = 65\text{ A}$.

Q2: E_{AS} of 661 mJ is based on starting $T_J = 25\text{ }^\circ\text{C}$, $L = 3\text{ mH}$, $I_{AS} = 21\text{ A}$, $V_{DD} = 30\text{ V}$, $V_{GS} = 10\text{ V}$. 100% tested at $L = 0.1\text{ mH}$, $I_{AS} = 65\text{ A}$.

4. Pulsed I_d please refer to Fig 11 SOA graph for more details.

5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics (Q1 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted.

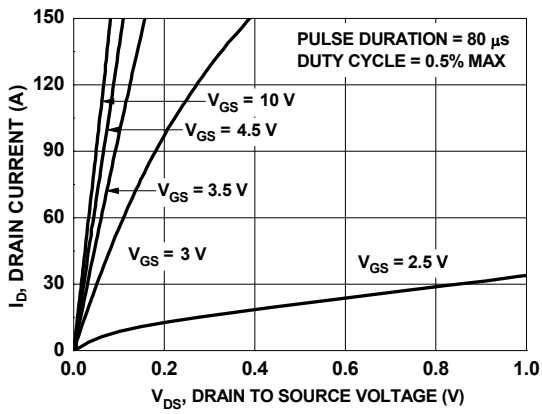


Figure 1. On Region Characteristics

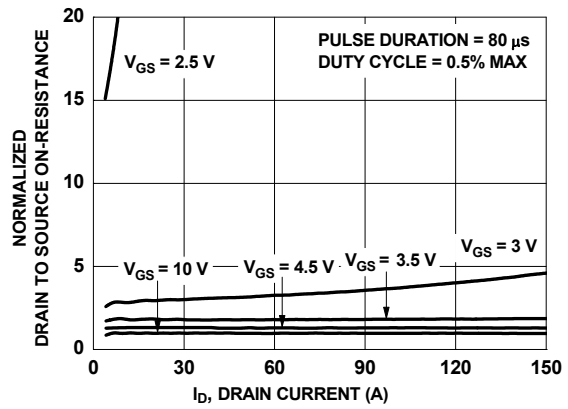


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

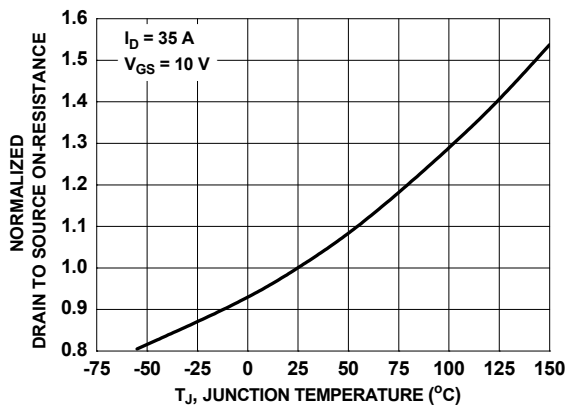


Figure 3. Normalized On Resistance vs. Junction Temperature

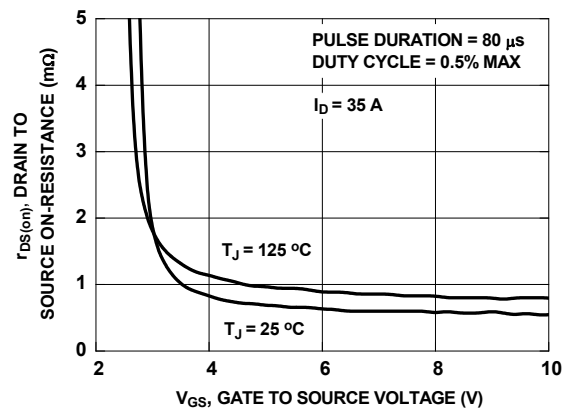


Figure 4. On-Resistance vs. Gate to Source Voltage

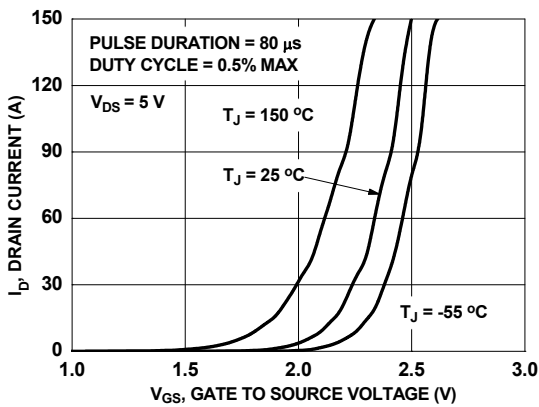


Figure 5. Transfer Characteristics

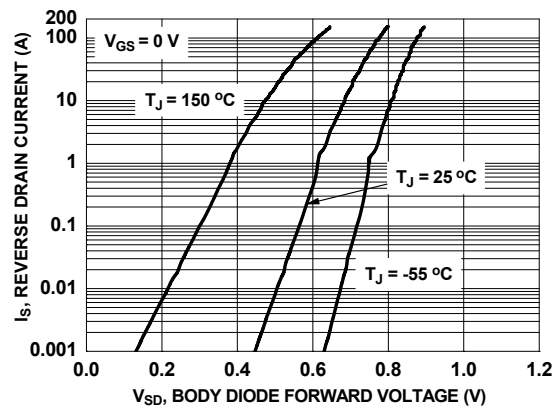


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics (Q1 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted.

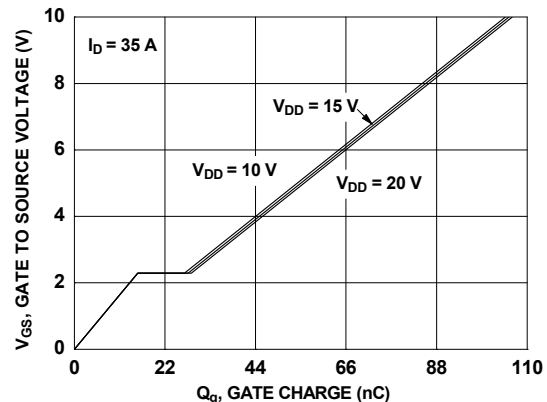


Figure 7. Gate Charge Characteristics

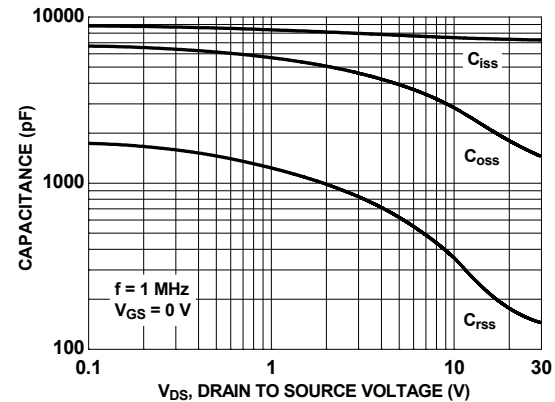


Figure 8. Capacitance vs. Drain to Source Voltage

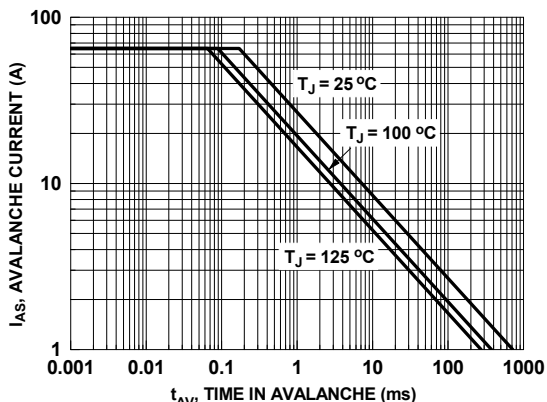


Figure 9. Unclamped Inductive Switching Capability

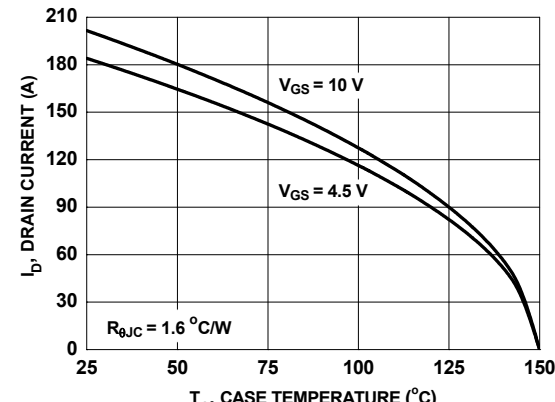


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

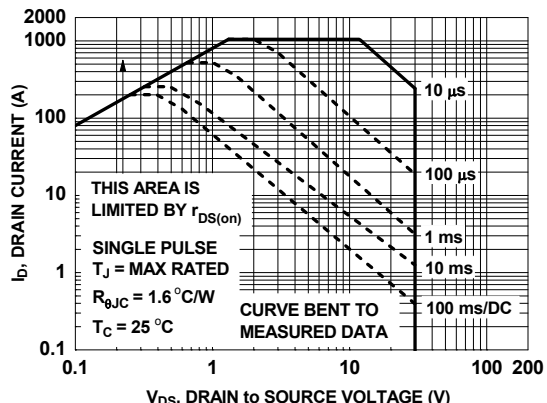


Figure 11. Forward Bias Safe Operating Area

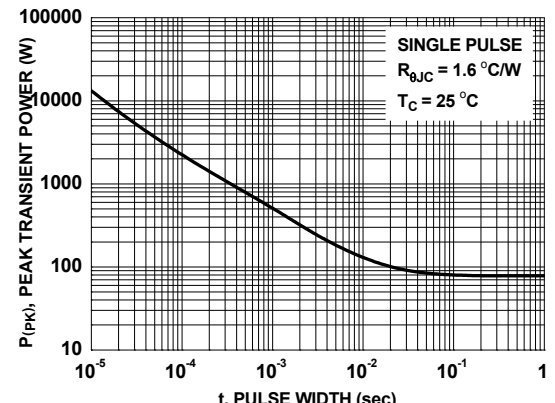


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q1 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted.

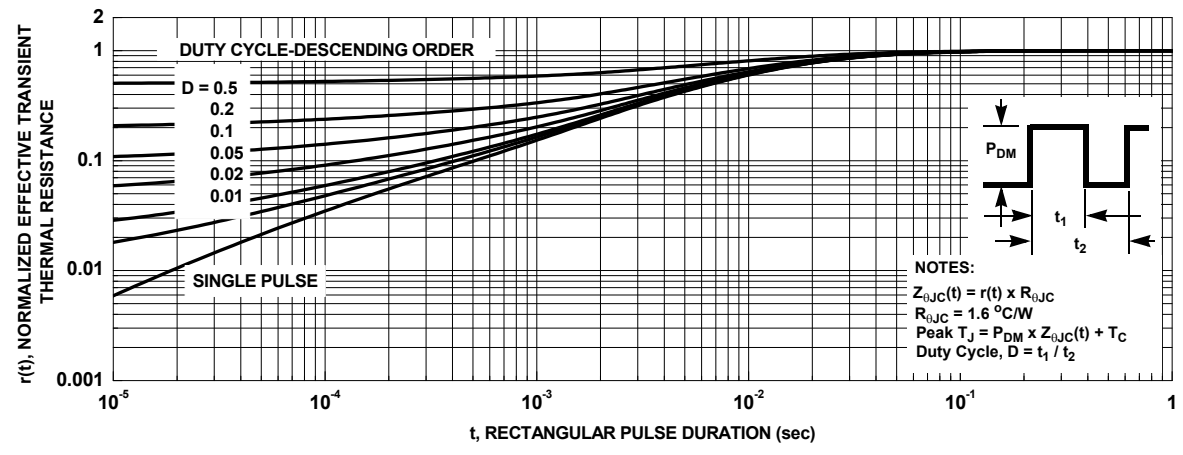


Figure 13. Junction-to-Case Transient Thermal Response Curve

Typical Characteristics (Q2 N-Channel) $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted.

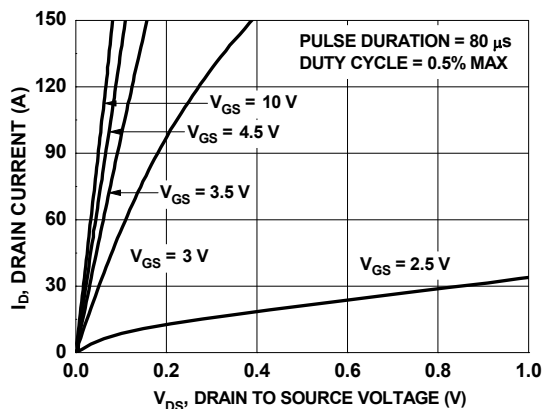


Figure 14. On-Region Characteristics

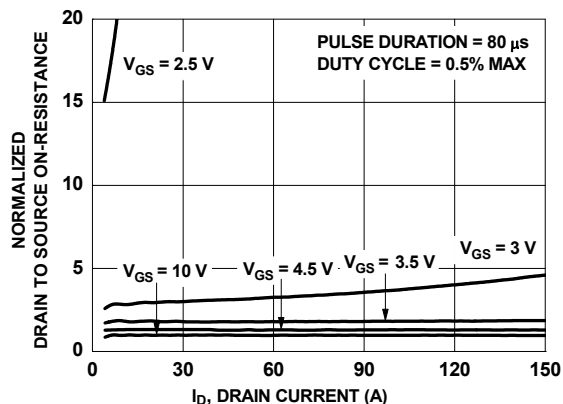


Figure 15. Normalized on-Resistance vs. Drain Current and Gate Voltage

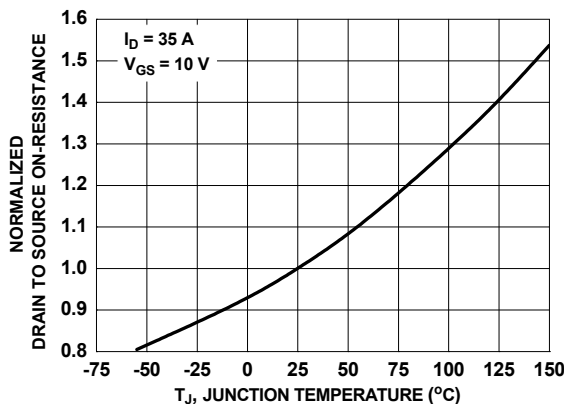


Figure 16. Normalized On-Resistance vs. Junction Temperature

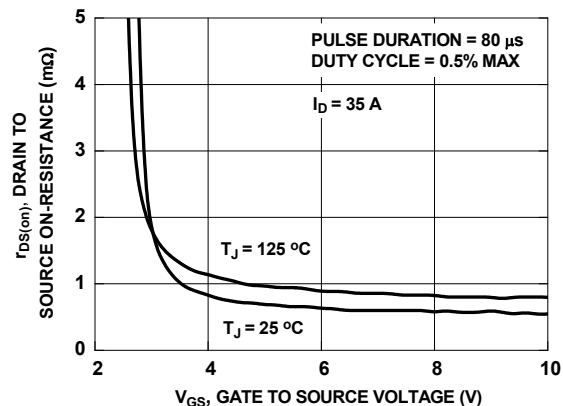


Figure 17. On-Resistance vs. Gate to Source Voltage

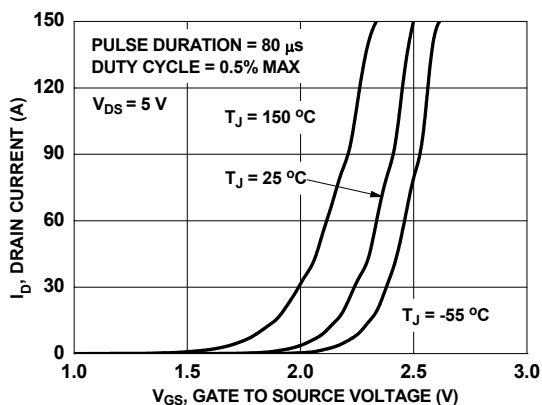


Figure 18. Transfer Characteristics

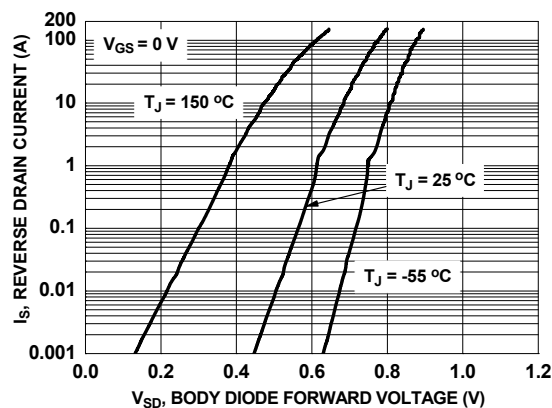


Figure 19. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics (Q2 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted.

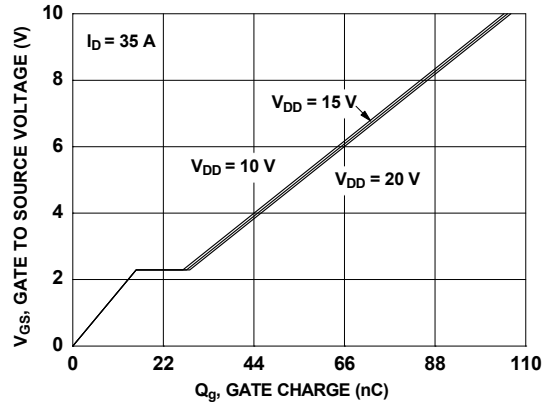


Figure 20. Gate Charge Characteristics

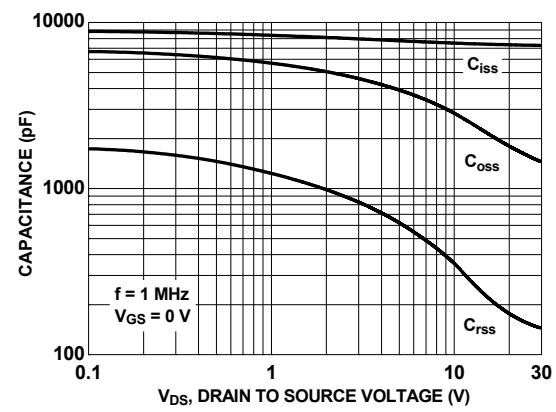


Figure 21. Capacitance vs. Drain to Source Voltage

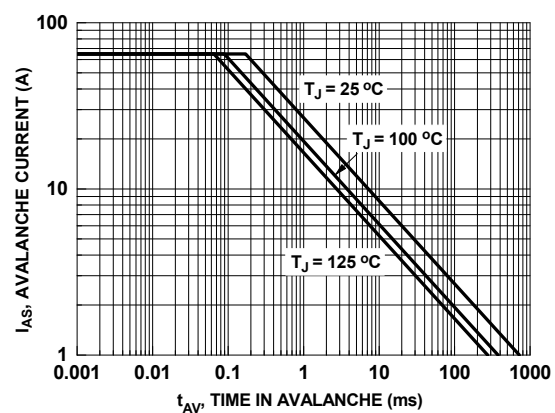


Figure 22. Unclamped Inductive Switching Capability

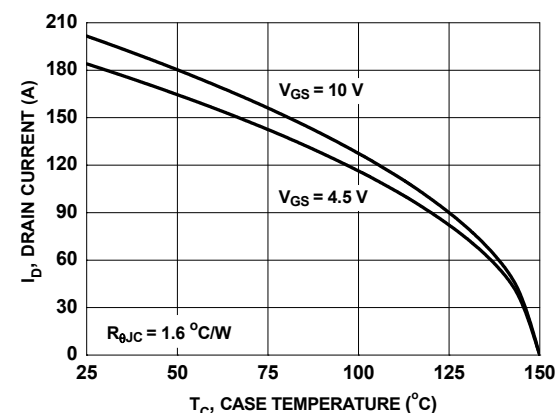


Figure 23. Maximum Continuous Drain Current vs. Case Temperature

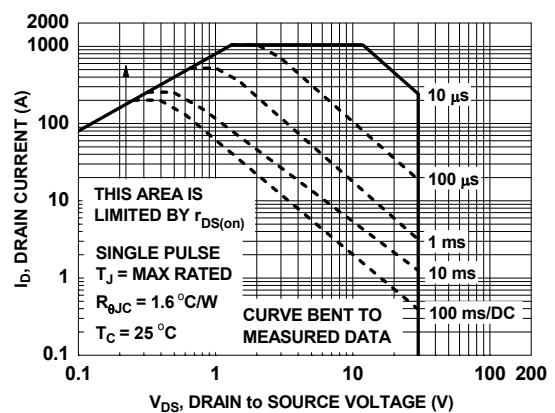


Figure 24. Forward Bias Safe Operating Area

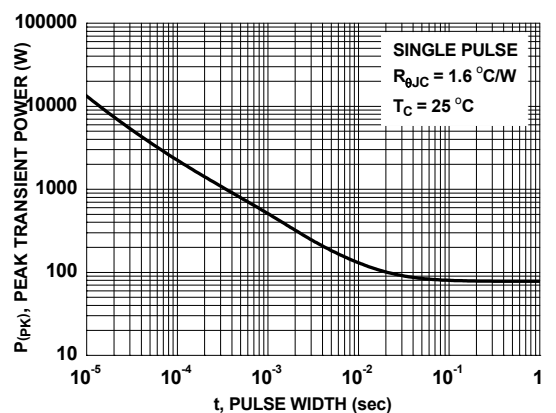


Figure 25. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q2 N-Channel) $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted.

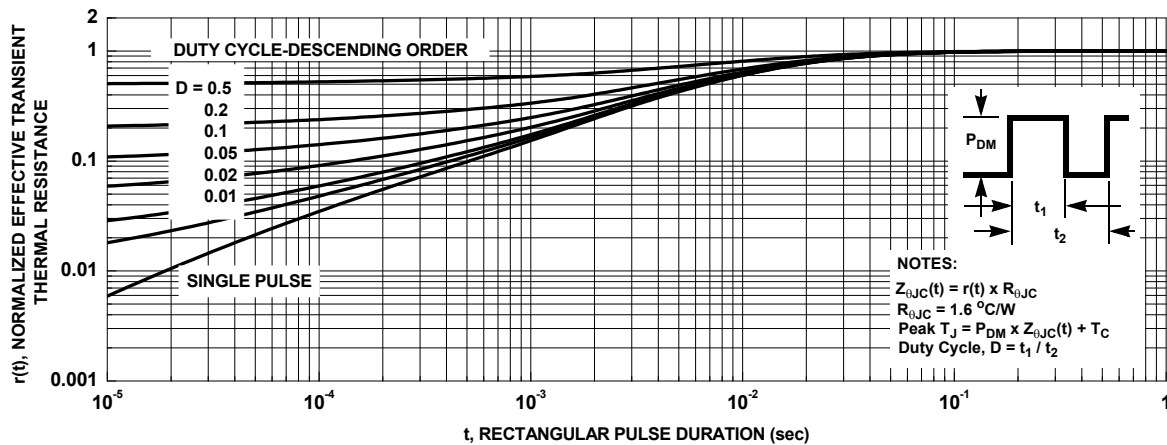
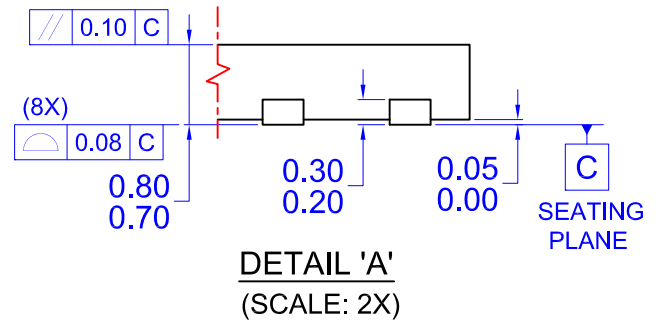
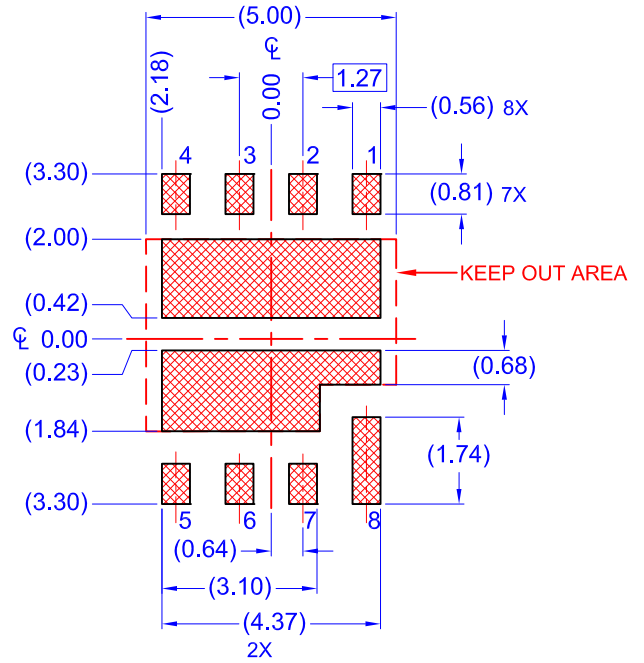
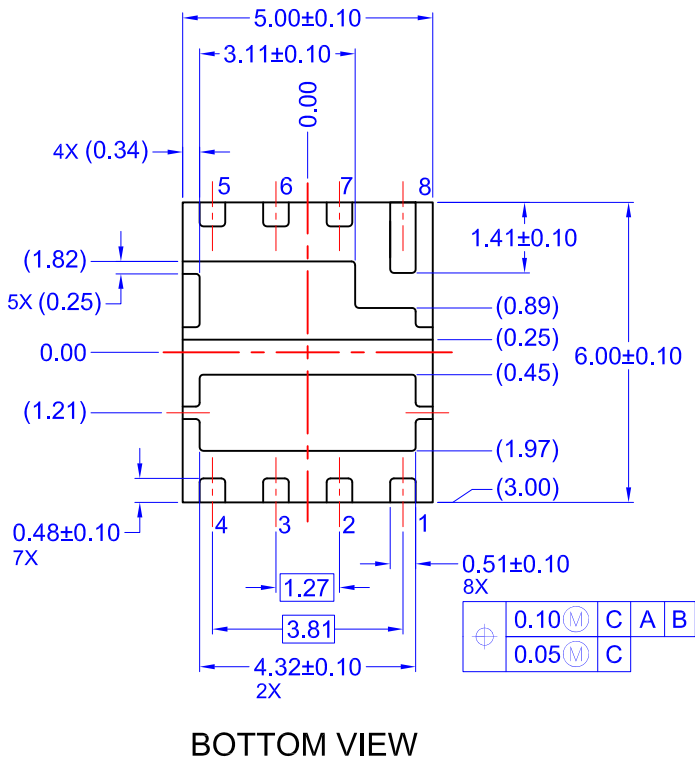
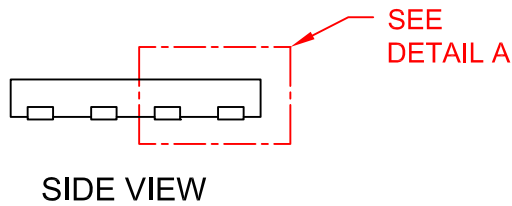
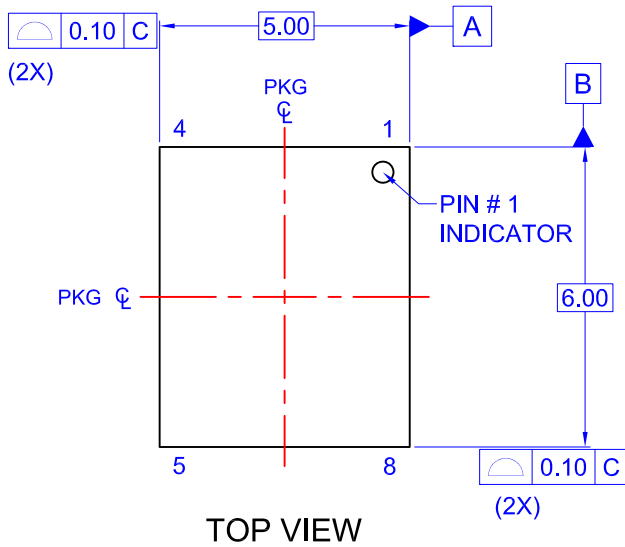


Figure 26. Junction-to-Case Transient Thermal Response Curve



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) PACKAGE STANDARD REFERENCE: JEDEC REGISTRATION, MO-240, VARIATION AA.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
 - D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
 - E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.
 - F) DRAWING FILE NAME: MKT-PQFN08QREV2





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| ESBC™ | MicroPak2™ | STEALTH™ | UniFET™ |
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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